



2831/

I hereby certify that this correspondence is being deposited with the United States Postal Service on the date set forth below as First Class Mail in an envelope addressed to: Box Amendment; Commissioner for Patents, Washington, D. C. 20231.

Date of Signature and Deposit: March 18, 2003

Alan J. [Signature]
Attorney of Record

*6 of 6
Chenusa
2/1-03*

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Richard D. Harris, et al.
Serial No.: 09/842,975
Filed: 04/26/2001
Examiner: Eric W. Thomas
Group Art Unit: 2831
Docket No.: 110003.97397
Title: *Method for Fabricating an Isolated Microelectromechanical System (MEMS) Device Incorporating a Wafer Level Cap*

AMENDMENT

BOX AMENDMENT

Commissioner for Patents

04/01/2003 TDRKZMS 0000002 170055 20030342975

01 FC:1201

Dear Sir:

In response to the Office Action dated December 19, 2002, please amend the above-identified patent application as follows and consider the following remarks:

IN THE CLAIMS

Please amend the claims as indicated below. A version of the claims with markings to show changes made is attached to the end of this communication.

1. (Once Amended) A MEMS structure comprising:
- a substrate;
 - at least one conductive element that is in mechanical communication with the substrate and that extends therefrom;
 - a movable MEMS element having a portion that is free from the substrate and positioned such that a variable-sized gap extends substantially parallel to the substrate and separates the movable MEMS element from the at least one conductive element;

03/27/2003 CNGUYEN 00000015 170055 09842975

01 FC:1202
02 FC:1201

918.00 CH
420.00 CH

RECEIVED
MAR 23 2003
TO 2003 MAIL ROOM

a'